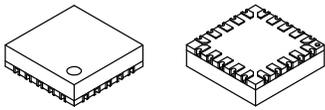


MECHANICAL CASE OUTLINE

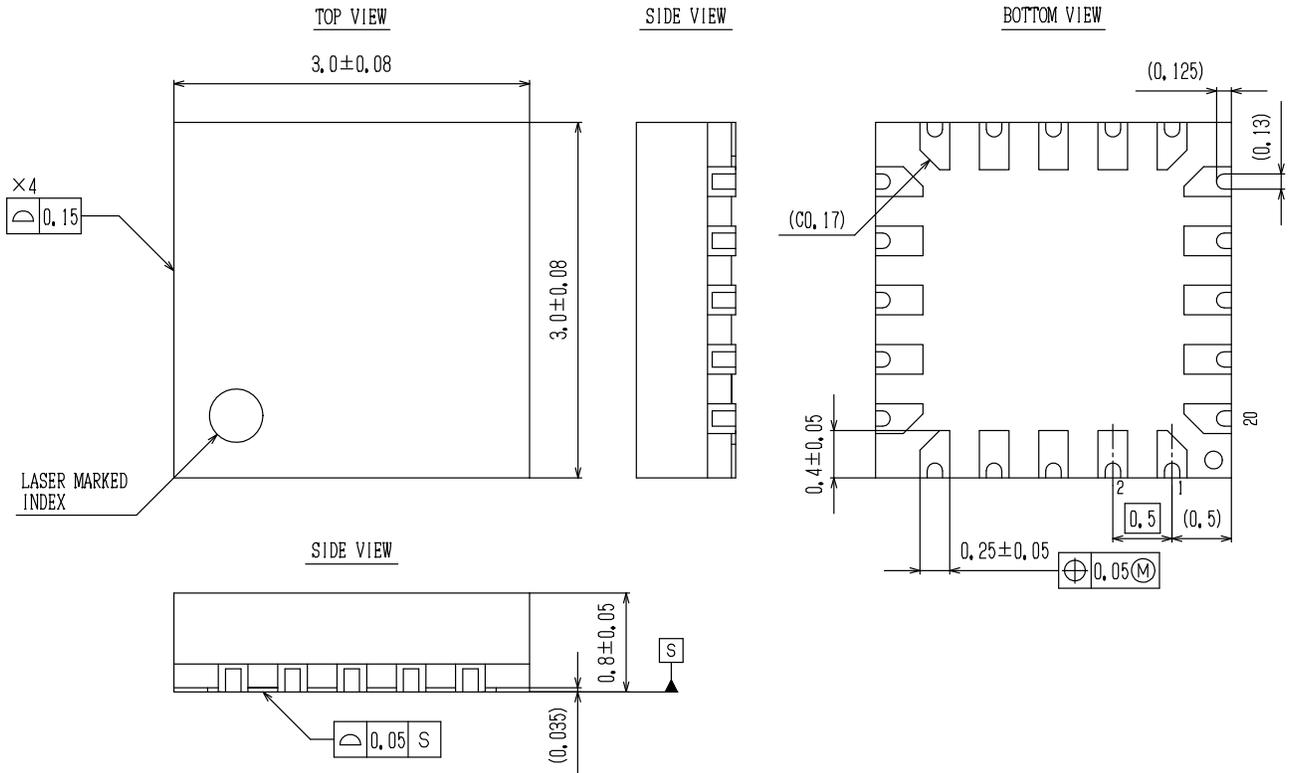
PACKAGE DIMENSIONS

ON Semiconductor®

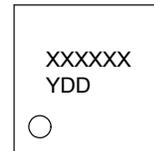
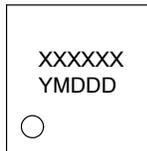


VCT20 3x3, 0.5P
CASE 601AB
ISSUE A

DATE 15 NOV 2013



GENERIC MARKING DIAGRAM*



XXXXXX = Specific Device Code
 Y = Year
 M = Month
 DDD = Additional Traceability Data

XXXXXX = Specific Device Code
 Y = Year
 DD = Additional Traceability Data

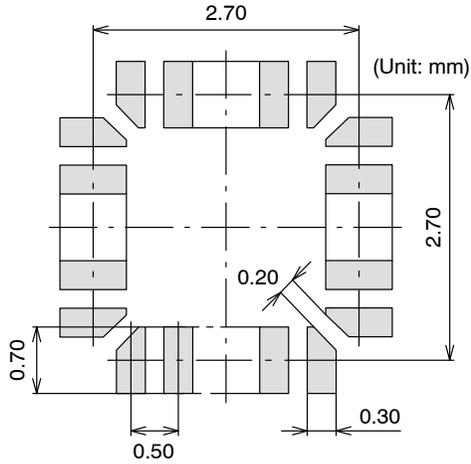
*This information is generic. Please refer to device data sheet for actual part marking.
 Pb-Free indicator, "G" or microdot "▪", may or may not be present.

DOCUMENT NUMBER:	98AON78679E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	VCT20 3X3, 0.5P	PAGE 1 OF 3

VCT20 3x3, 0.5P
CASE 601AB
ISSUE A

DATE 15 NOV 2013

SOLDERING FOOTPRINT*



NOTE: The measurements are not to guarantee but for reference only.

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON78679E	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	VCT20 3X3, 0.5P	PAGE 2 OF 3

